

# MA21D350G

## Silicon epitaxial planar type

For rectification

### ■ Features

- Forward current (Average)  $I_{F(AV)} = 1.0$  A rectification is possible
- Low reverse current  $I_R$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current (Average)	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *	$I_{FSM}$	20	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

### ■ Package

- Code  
SMini2-F2
- Pin Name  
1: Anode  
2: Cathode

### ■ Marking Symbol: 4W

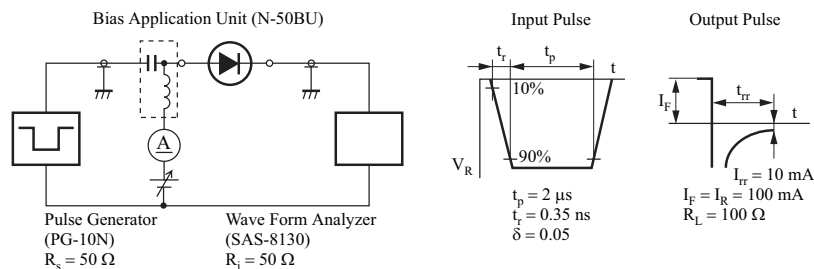
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

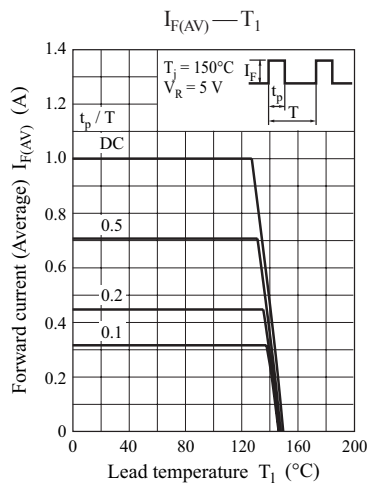
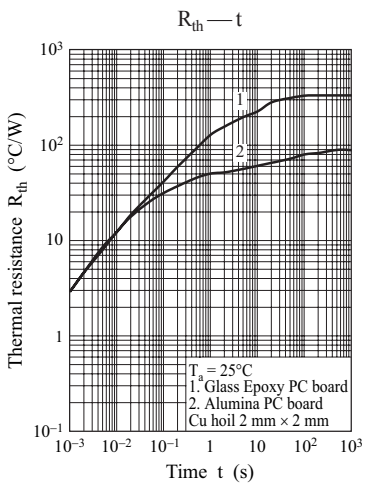
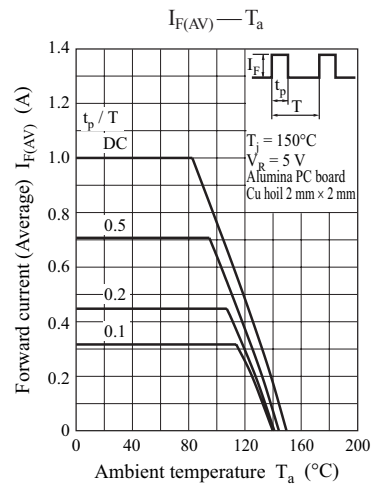
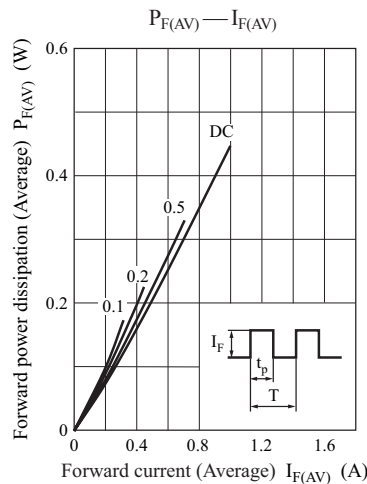
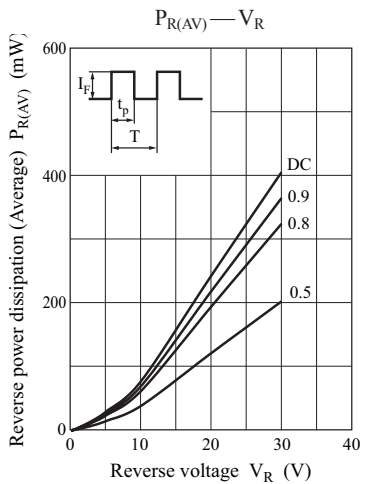
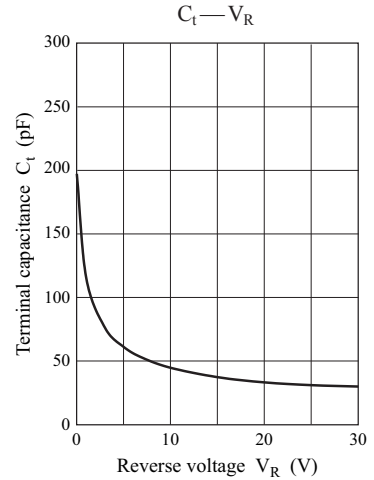
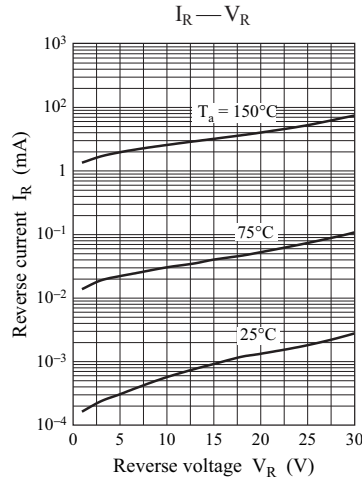
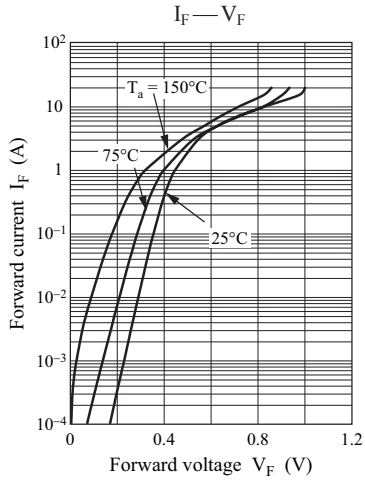
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 0.7$ A		0.42	0.47	V
	$V_{F2}$	$I_F = 1.0$ A		0.44	0.49	
Reverse current	$I_R$	$V_R = 30$ V			40	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 10$ V, $f = 1$ MHz		43		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA, $I_{rr} = 10$ mA, $R_L = 100 \Omega$		13		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

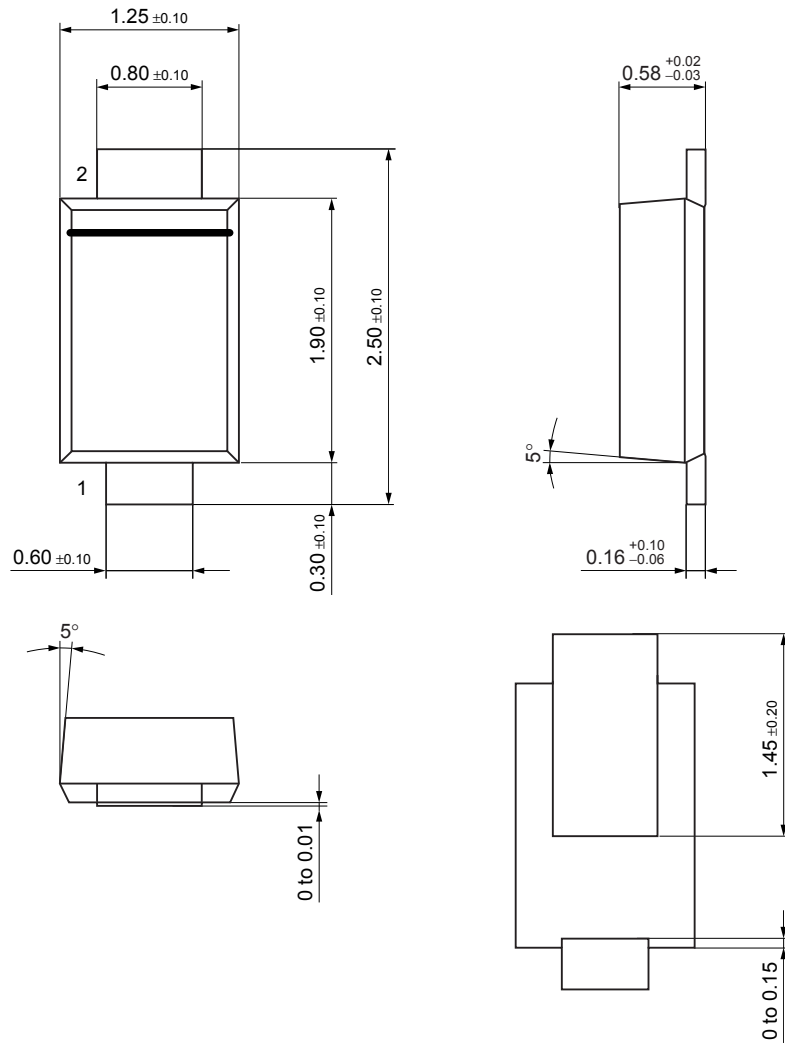
3. \*:  $t_{rr}$  measurement circuit





SMini2-F2

Unit: mm



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